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(12) **United States Design Patent** (10) **Patent No.:** **US D895,075 S**  
**Kang et al.** (45) **Date of Patent:** **\*\* Sep. 1, 2020**

(54) **SEAL MEMBER FOR SEMICONDUCTOR PRODUCTION APPARATUS**

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(73) Assignee: **Valqua, Ltd.**, Tokyo (JP)

(\*\*) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** ..... **23-01**

(52) **U.S. Cl.**  
USPC ..... **D23/269**

(58) **Field of Classification Search**  
USPC ..... D23/269; D8/382  
CPC ..... F16J 15/32; Y10T 428/215  
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a seal member for semiconductor production apparatus, as shown and described.

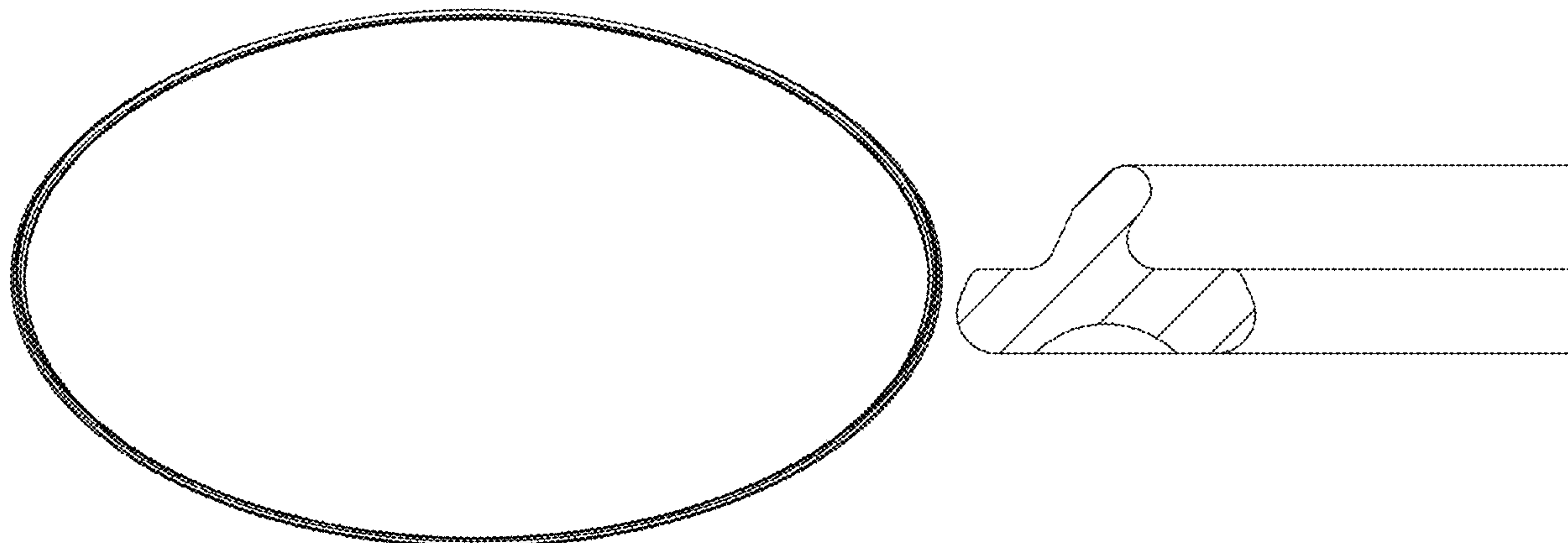
**DESCRIPTION**

- 1.1 : Perspective
- 1.2 : Front
- 1.3 : Back
- 1.4 : Left
- 1.5 : Right
- 1.6 : Top
- 1.7 : Bottom
- 1.8 : Cross-sectional
- 1.9 : Partial enlargement of cross-sectional view 1.8
- 1.10 : Reference

The present article is a seal member for semiconductor production apparatuses, such as chemical vapor deposition apparatuses and dry etching apparatuses; as illustrated in the reproduction 1.10, the article is to be inserted into the groove of a semiconductor production apparatus; the semiconductor production apparatus itself forms no part of the claimed design; the reproduction 1.8 shows a transverse cross-sectional front view taken along the horizontal center of the reproduction 1.6; and the reproduction 1.9 is an enlarged view showing a left end portion of the cross-sectional view 1.8.

The broken lines shown in Reproduction 1.10 are for the purposes of illustrating environmental structure and form no part of the claimed design.

**1 Claim, 10 Drawing Sheets**



(56)

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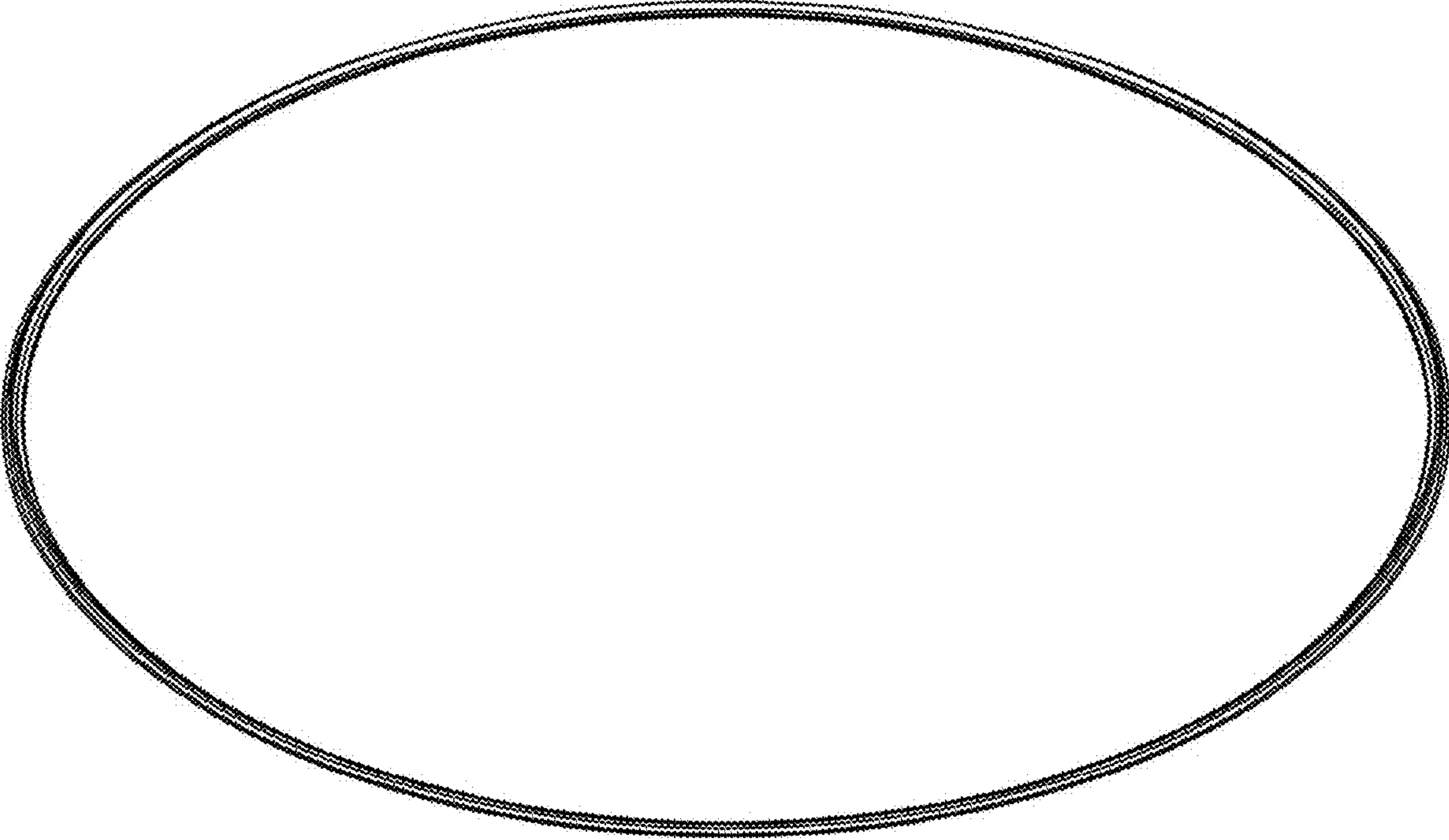
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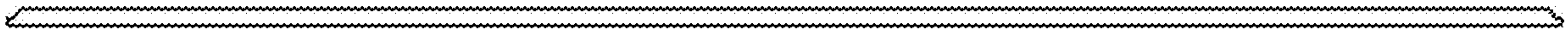
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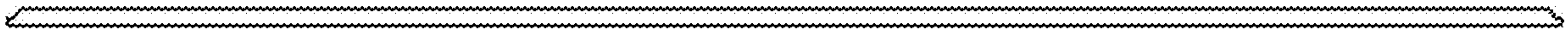
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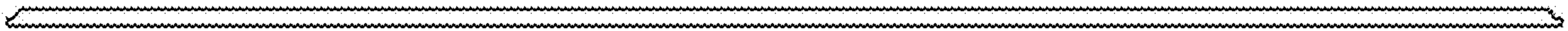
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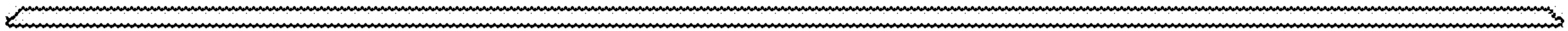
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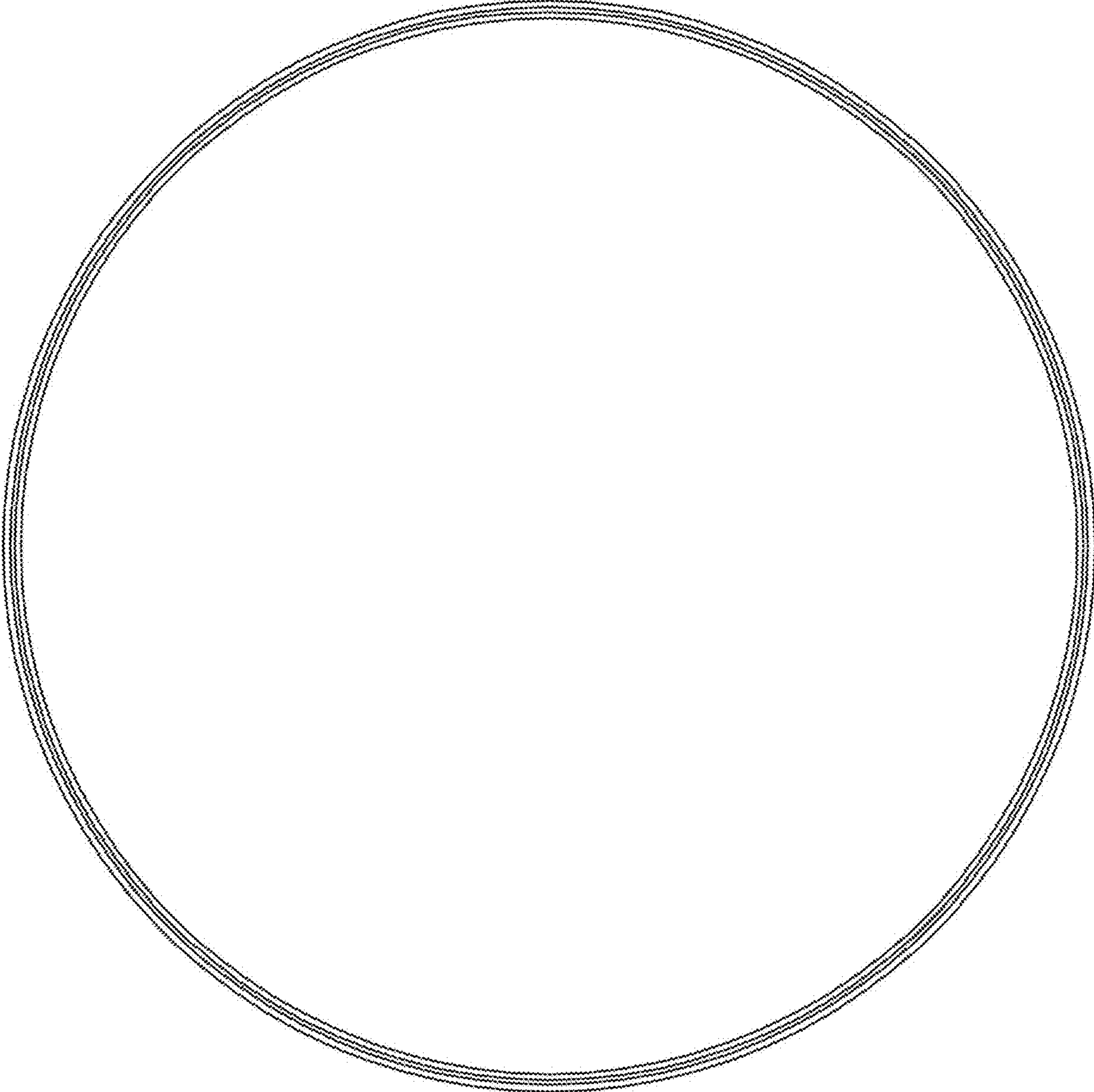
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**1.5**

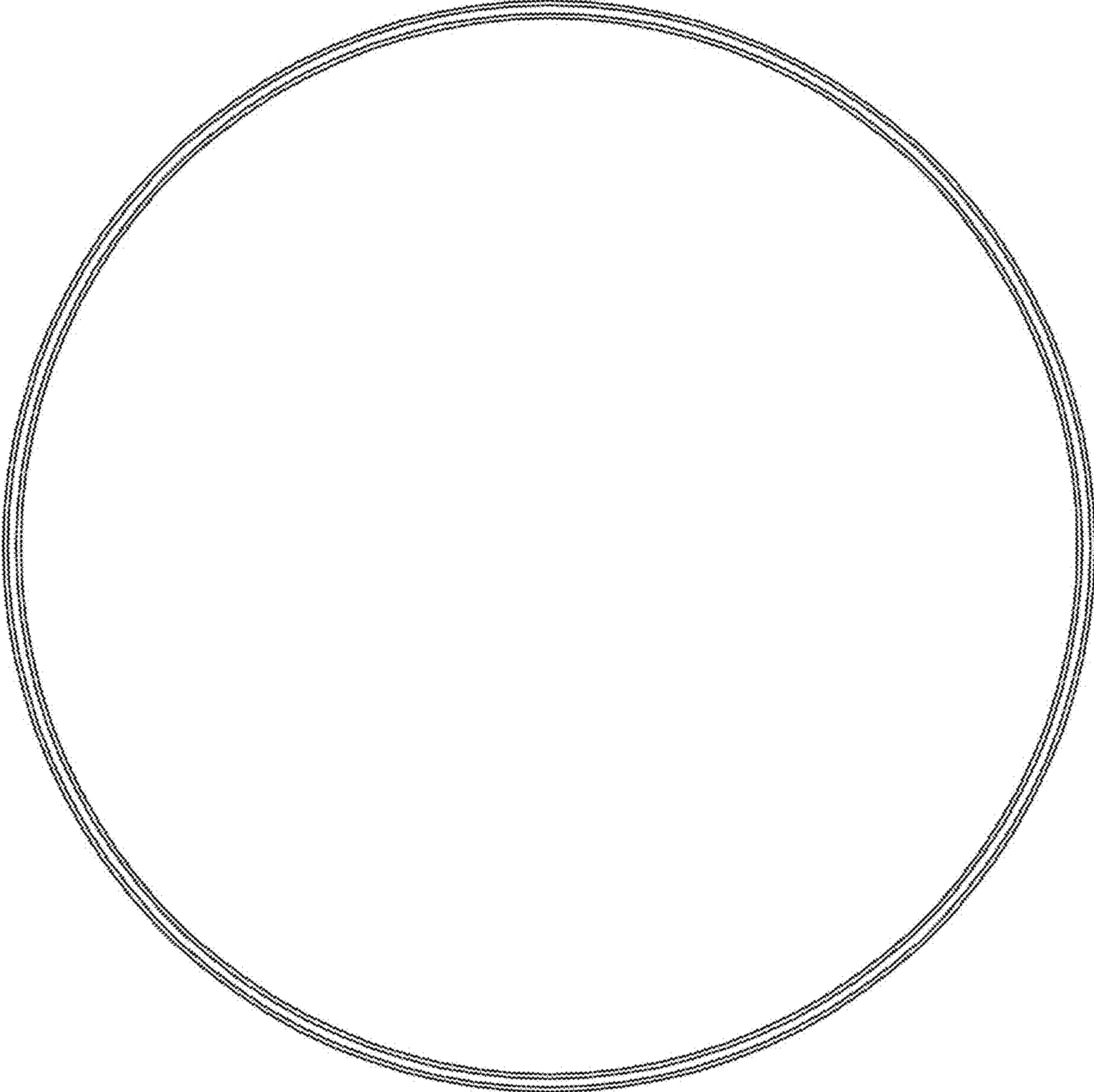


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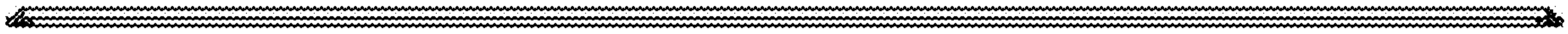




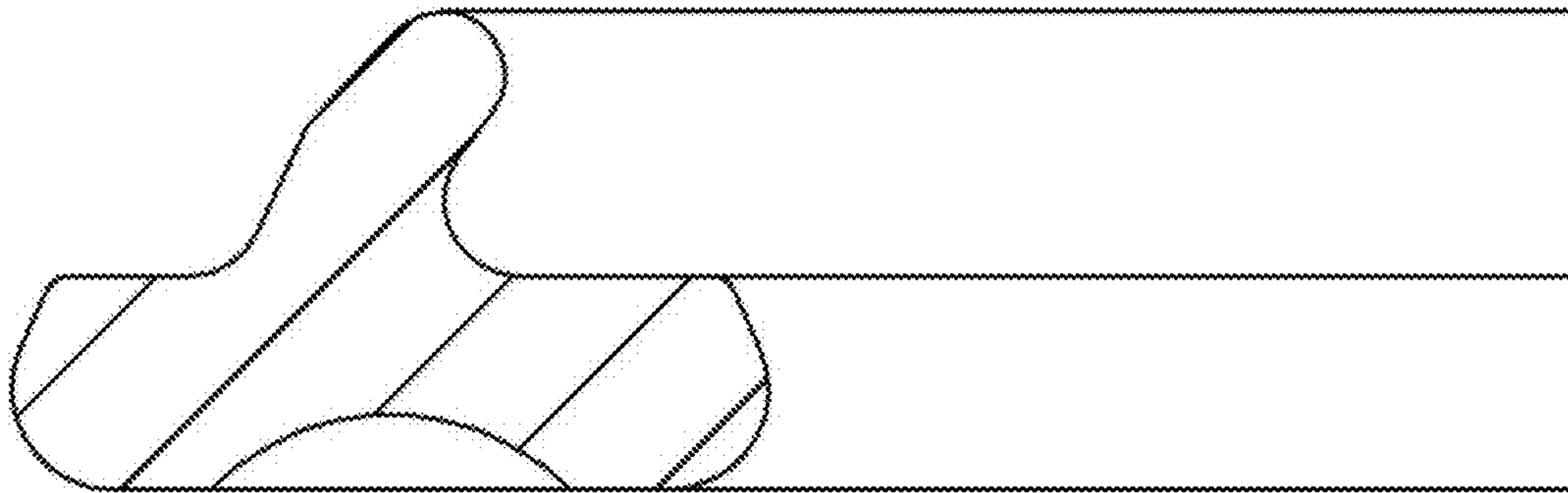
1.7



1.8



1.9



1.10

